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<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b> (Use several sheets if necessary)		APPLICANT William Franklin Burgoyne, Jr., et al.	
		FILING DATE	GROUP

(37 CFR 1.98(b))














## U.S. PATENT DOCUMENTS

EXAM- INER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

## FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
					YES NO

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

            	J. H. Lau, "A Brief Introduction Flip Chip Technologies for Multichip Module Applications," <i>Flip Chip Technologies</i> , Mc-Graw Hill, New York (1995)
	R. Tummala, "Microelectronics Packaging - An Overview," <i>Microelectronics Handbook, Part 1</i> , Ed. International Thompson Publishing, 2 <sup>nd</sup> Edition, New York (1997)
	K. Gilleo, "Introduction to Conductive Adhesive Joining Technology," <i>Conductive Adhesives for Electronics Packaging</i> , Electrochemical Publications, British Isles (1999)
	R. Ghaffarian, "Close the Information Gap on IC-Package Reliability," <i>Electronic Design</i> , Vol. 46, No. 18, pp. 71-72 (Aug. 3, 1998)
	J. Ivan, et al., "Moisture and Thermal Degradation of Cyanate-Ester-Based Die Attach Material," <i>Proceedings of the 1997 Electronic Components and Technology Conference</i> , 1997, pp. 525-535
	I. Y. Chien, et al., "Low Stress Polymer Die Attach Adhesives for Plastic Packages," <i>Proceedings of the 1994 Electronic Components and Technology Conference</i> , 1994, pp. 580-584
	D. P. Galloway, et al., "Reliability of Novel Die Attach Adhesives for Snap Curing," <i>Proceedings of the IEEE/CPMT International Electronic Manufacturing Technology (IEMT) Symposium</i> , 1995, pp. 141-147
	A. Javidinejad, et al., "Application of Electrically Conductive Thermoplastic Adhesive Film for Design and Manufacturing of Smart Structures," <i>SPIE Proceedings Smart Structures and Integrated Systems</i> , Vol. 3668, March 1999, pp. 688-695
	D. Lu, et al., "Conductive Adhesives Based on Anhydride-Cured Epoxy Systems," <i>Proceedings of the 2<sup>nd</sup> International IEEE Symposium on Polymeric Electronics Packaging</i> , 1999
	K. Gilleo, "Assembly With Conductive Adhesives," <i>Soldering and Surface Mount Technology</i> , No. 19, Feb. 1995, pp. 12-17
	P. G. Harris, "Conductive Adhesives: A Critical Review of Progress to Date," <i>Soldering and Surface Mount Technology</i> , No. 20, May 1995, pp. 19-21
	J. C. Jagt, et al., "Electrically Conductive Adhesives: A Prospective Alternative for SMD Soldering?," <i>IEEE Transactions on Components, Packaging and Manufacturing Technology - Part B Advanced Packaging</i> , Vol. 18, No. 2, pp. 292-297 (May 1995)
	J. Jagt, "Reliability of Electrically Conductive Adhesive Joints for Surface Mount Applications," <i>IEEE Transactions on Components, Packaging and Manufacturing Technology - Part A</i> , Vol. 21, No. 2, pp. 215-225 (June 1998)

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.